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DERWENT-WEEK: 200305

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**TITLE: Apparatus for baking photosensitive resist
deposited on
semiconductor wafer, comprises hot plate for
generating
heat**

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PATENT-FAMILY:

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MAIN-IPC			
KR 99033495 A	May 15, 1999	N/A	000
H01L 021/027			
KR 275723 B	January 15, 2001	N/A	000
H01L 021/027			
TW 436890 A	May 28, 2001	N/A	000
H01L 021/027			

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
KR 99033495A	N/A	1997KR-0054864
October 24, 1997		

KR 275723B	N/A	1997KR-0054864	
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KR 275723B	Previous Publ.	KR 99033495	N/A
TW 436890A	N/A	1998TW-0115740	
September 22, 1998			

INT-CL (IPC): H01L021/027

ABSTRACTED-PUB-NO: KR 99033495A

BASIC-ABSTRACT:

NOVELTY - An apparatus for baking a photosensitive resist deposited on a semiconductor wafer, comprises a hot plate for generating heat to bake the resist, a plurality of spacers for supporting the wafer to be spaced over the hot plate with variable distance, the spacers having the upper end part abutting with the edge of the wafer and the lower end part connected with the hot plate, and spacer movement means for raising or lowering the spacers to adjust the interval between the wafer and hot plate. Each of the spacers has a cylindrical from with peripherally spiral grooves connected with corresponding spirally grooved hole formed in the hot plate, and the spacer movement means includes a grip formed on the lower end part of each spacer. The grip is used to raise or lower the corresponding spacer by rotating. Each of

the spacers

includes a stopper provided at the upper end to support the periphery of the wafer.

ABSTRACTED-PUB-NO: TW 436890A

EQUIVALENT-ABSTRACTS:

NOVELTY - An apparatus for baking a photosensitive resist deposited on a semiconductor wafer, comprises a hot plate for generating heat to bake the resist, a plurality of spacers for supporting the wafer to be spaced over the hot plate with variable distance, the spacers having the upper end part abutting with the edge of the wafer and the lower end part connected with the hot plate, and spacer movement means for raising or lowering the spacers to adjust the interval between the wafer and hot plate. Each of the spacers has a cylindrical form with peripherally spiral grooves connected with corresponding spirally grooved hole formed in the hot plate, and the spacer movement means includes a grip formed on the lower end part of each spacer. The grip is used to raise or lower the corresponding spacer by rotating. Each of the spacers includes a stopper provided at the upper end to support the periphery of the wafer.

CHOSEN-DRAWING: Dwg.0/1 Dwg.0/1

**TITLE-TERMS: APPARATUS BAKE PHOTSENSITISER RESIST
DEPOSIT SEMICONDUCTOR WAFER
COMPRISE HOT PLATE GENERATE HEAT**

DERWENT-CLASS: U11

EPI-CODES: U11-C04A1B; U11-C09F;

SECONDARY-ACC-NO:

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